



PMF170XP

20 V, 1 A P-channel Trench MOSFET

29 October 2013

Product data sheet

1. General description

P-channel enhancement mode Field-Effect Transistor (FET) in a SOT323 (SC-70) small Surface-Mounted Device (SMD) plastic package using Trench MOSFET technology.

2. Features and benefits

- Low R_{DSon}
- Very fast switching
- Trench MOSFET technology

3. Applications

- Relay driver
- High-speed line driver
- High-side loadswitch
- Switching circuits

4. Quick reference data

Table 1. Quick reference data

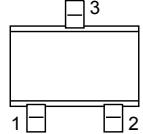
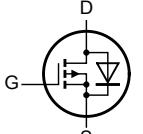
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25^\circ\text{C}$		-	-	-20	V
V_{GS}	gate-source voltage			-12	-	12	V
I_D	drain current	$V_{GS} = -4.5\text{ V}$; $T_{amb} = 25^\circ\text{C}$	[1]	-	-	-1	A
Static characteristics							
R_{DSon}	drain-source on-state resistance	$V_{GS} = -4.5\text{ V}$; $I_D = -1\text{ A}$; $T_j = 25^\circ\text{C}$		-	175	200	$\text{m}\Omega$

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm^2 .

nexperia

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	G	gate		
2	S	source		
3	D	drain	 SC-70 (SOT323)	 017aaa094

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMF170XP	SC-70	plastic surface-mounted package; 3 leads	SOT323

7. Marking

Table 4. Marking codes

Type number	Marking code
PMF170XP	[1] XD%

[1] % = placeholder for manufacturing site code

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage	$T_j = 25^\circ\text{C}$	-	-20	V
V_{GS}	gate-source voltage		-12	12	V
I_D	drain current	$V_{GS} = -4.5\text{ V}; T_{amb} = 25^\circ\text{C}$	[1]	-1	A
		$V_{GS} = -4.5\text{ V}; T_{amb} = 100^\circ\text{C}$	[1]	-0.7	A
I_{DM}	peak drain current	$T_{amb} = 25^\circ\text{C}$; single pulse; $t_p \leq 10\ \mu\text{s}$	-	-4	A
P_{tot}	total power dissipation	$T_{amb} = 25^\circ\text{C}$	[2]	290	mW
			[1]	360	mW
		$T_{sp} = 25^\circ\text{C}$	-	1670	mW
T_j	junction temperature		-55	150	°C

Symbol	Parameter	Conditions	Min	Max	Unit
T _{amb}	ambient temperature		-55	150	°C
T _{stg}	storage temperature		-65	150	°C
Source-drain diode					
I _S	source current	T _{amb} = 25 °C	[1]	-	-0.4 A

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for drain 6 cm².
 [2] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

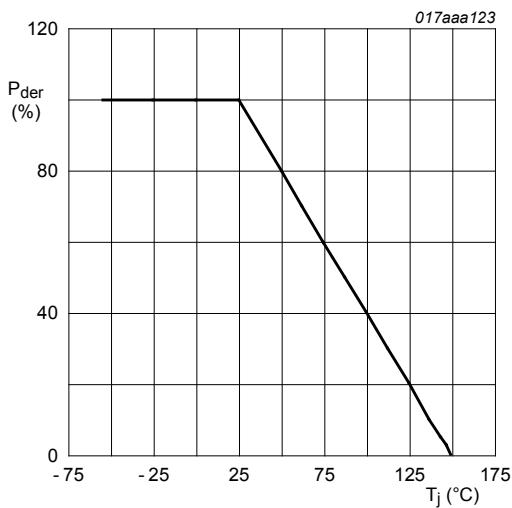


Fig. 1. Normalized total power dissipation as a function of junction temperature

$$P_{der} = \frac{P_{tot}}{P_{tot(25^\circ C)}} \times 100 \%$$

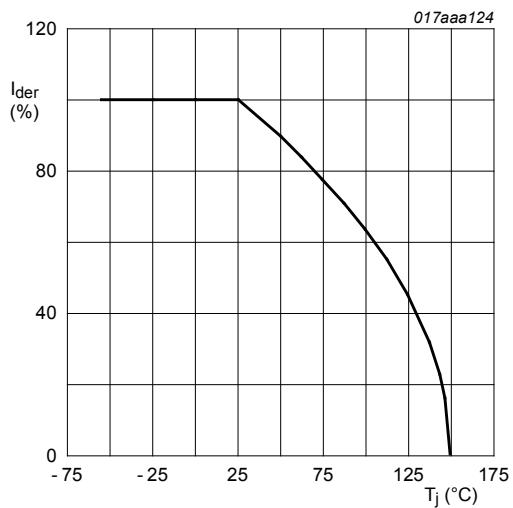


Fig. 2. Normalized continuous drain current as a function of junction temperature

$$I_{der} = \frac{I_D}{I_{D(25^\circ C)}} \times 100 \%$$

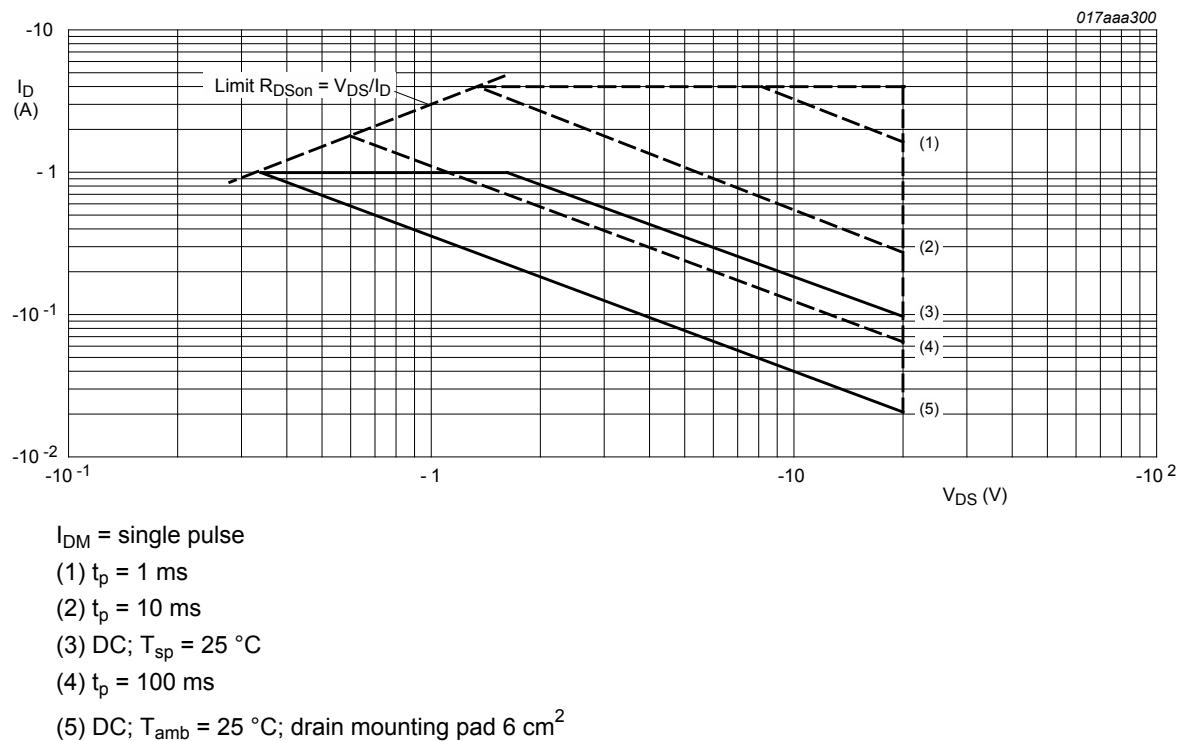


Fig. 3. Safe operating area; junction to ambient; continuous and peak drain currents as a function of drain-source voltage

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]	-	377	430	K/W
			[2]	-	305	350	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point			-	65	75	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for drain 6 cm^2 .

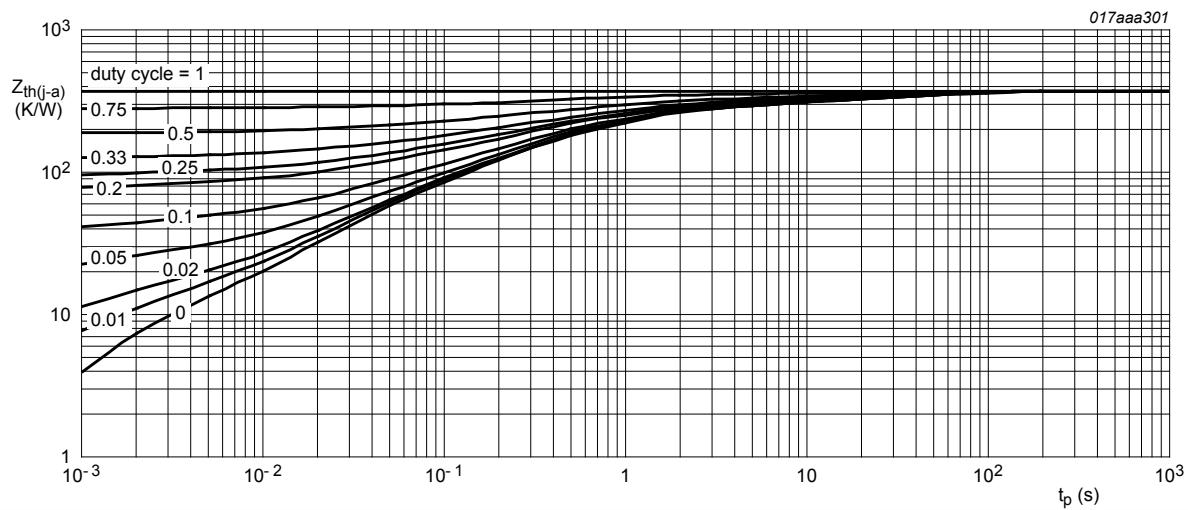


Fig. 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

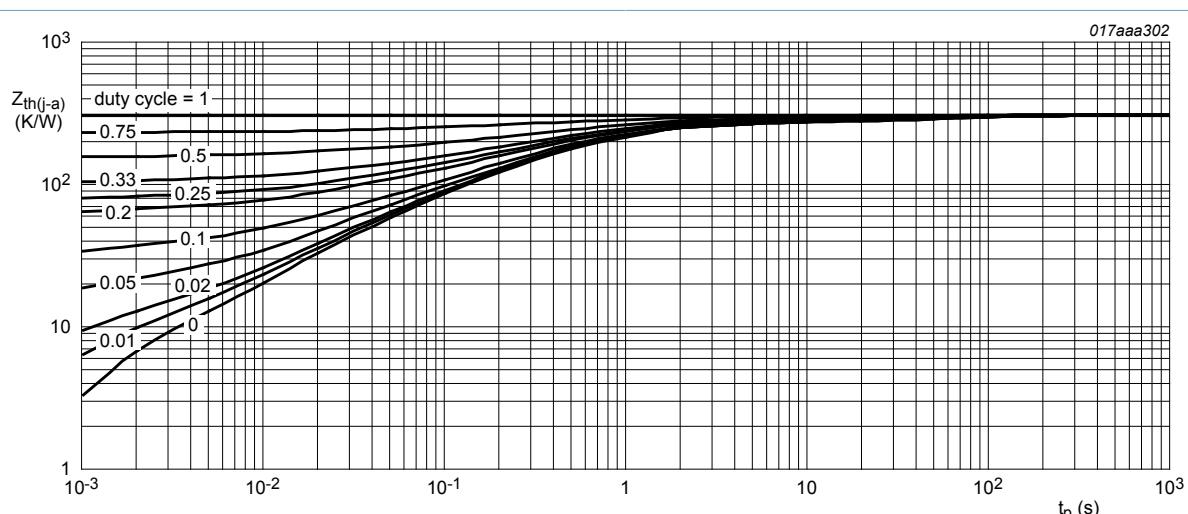


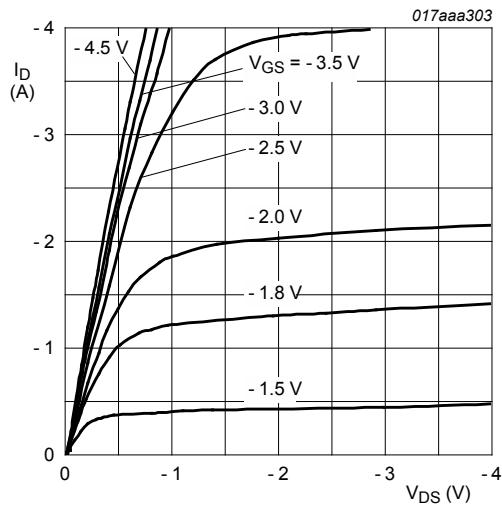
Fig. 5. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

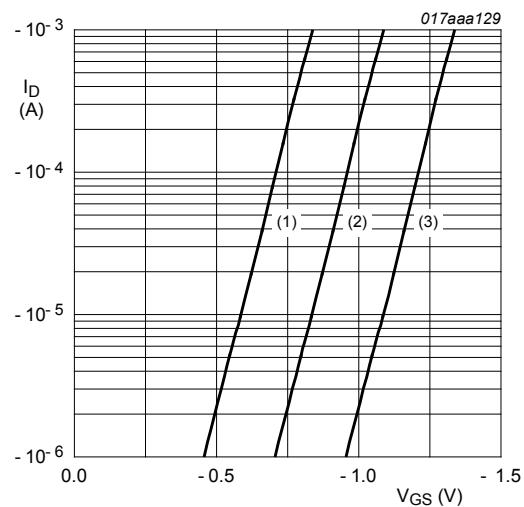
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = -250 \mu A; V_{GS} = 0 V; T_j = 25^\circ C$	-20	-	-	V
V_{GSth}	gate-source threshold voltage	$I_D = -250 A; V_{DS} = V_{GS}; T_j = 25^\circ C$	-0.65	-0.9	-1.15	V
I_{DSS}	drain leakage current	$V_{DS} = -20 V; V_{GS} = 0 V; T_j = 25^\circ C$	-	-	-1	μA
		$V_{DS} = -20 V; V_{GS} = 0 V; T_j = 150^\circ C$	-	-	-10	μA

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_{GSS}	gate leakage current	$V_{GS} = -12 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$		-	-	-100	nA
		$V_{GS} = 12 \text{ V}; V_{DS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$		-	-	-100	nA
R_{DSon}	drain-source on-state resistance	$V_{GS} = -4.5 \text{ V}; I_D = -1 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$		-	175	200	$\text{m}\Omega$
		$V_{GS} = -4.5 \text{ V}; I_D = -1 \text{ A}; T_j = 150 \text{ }^\circ\text{C}$		-	250	284	$\text{m}\Omega$
		$V_{GS} = -2.5 \text{ V}; I_D = -1 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$		-	240	300	$\text{m}\Omega$
g_{fs}	forward transconductance	$V_{DS} = -5 \text{ V}; I_D = -1 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$		-	1.9	-	S
Dynamic characteristics							
$Q_{G(\text{tot})}$	total gate charge	$V_{DS} = -10 \text{ V}; I_D = -1 \text{ A}; V_{GS} = -4.5 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$		-	2.6	3.9	nC
Q_{GS}	gate-source charge			-	0.63	-	nC
Q_{GD}	gate-drain charge			-	0.53	-	nC
C_{iss}	input capacitance	$V_{DS} = -10 \text{ V}; f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$		-	280	-	pF
C_{oss}	output capacitance			-	43	-	pF
C_{rss}	reverse transfer capacitance			-	30	-	pF
$t_{d(on)}$	turn-on delay time	$V_{DS} = -10 \text{ V}; I_D = -1 \text{ A}; V_{GS} = -4.5 \text{ V}; R_{G(\text{ext})} = 6 \Omega; T_j = 25 \text{ }^\circ\text{C}$		-	10	-	ns
t_r	rise time			-	16	-	ns
$t_{d(off)}$	turn-off delay time			-	31	-	ns
t_f	fall time			-	13	-	ns
Source-drain diode							
V_{SD}	source-drain voltage	$I_S = -0.4 \text{ A}; V_{GS} = 0 \text{ V}; T_j = 25 \text{ }^\circ\text{C}$		-	-0.7	-1.2	V



$T_j = 25^\circ\text{C}$

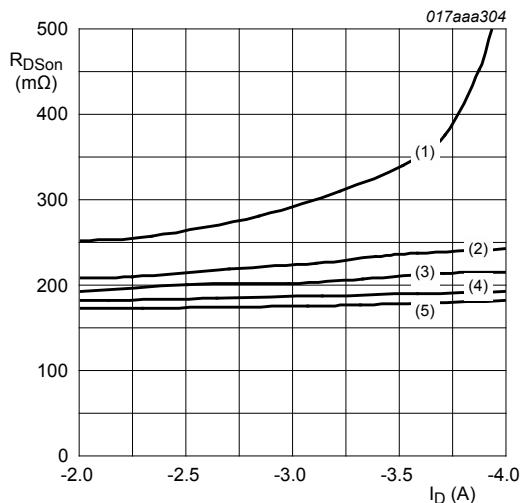
Fig. 6. Output characteristics: drain current as a function of drain-source voltage; typical values



$T_j = 25^\circ\text{C}; V_{DS} = -3\text{ V}$

- (1) minimum values
- (2) typical values
- (3) maximum values

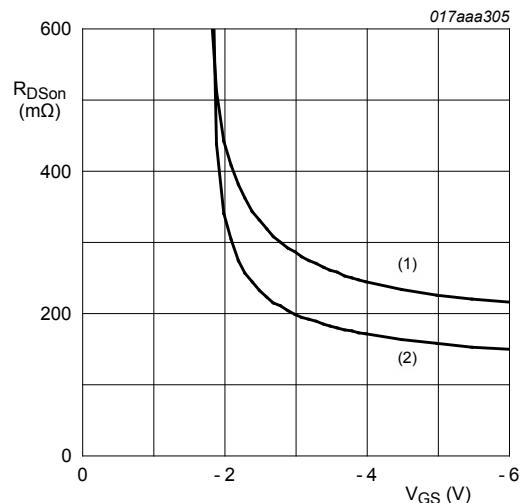
Fig. 7. Sub-threshold drain current as a function of gate-source voltage



$T_j = 25^\circ\text{C}$

- (1) $V_{GS} = -2.5\text{ V}$
- (2) $V_{GS} = -3.0\text{ V}$
- (3) $V_{GS} = -3.5\text{ V}$
- (4) $V_{GS} = -4.0\text{ V}$
- (5) $V_{GS} = -4.5\text{ V}$

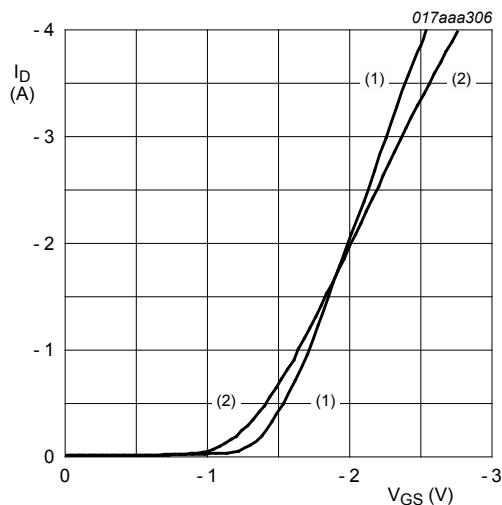
Fig. 8. Drain-source on-state resistance as a function of drain current; typical values



$I_D = -1\text{ A}$

- (1) $T_j = 150^\circ\text{C}$
- (2) $T_j = 25^\circ\text{C}$

Fig. 9. Drain-source on-state resistance as a function of gate-source voltage; typical values



$V_{DS} > I_D \times R_{DSon}$

- (1) $T_j = 25^\circ\text{C}$
- (2) $T_j = 150^\circ\text{C}$

Fig. 10. Transfer characteristics: drain current as a function of gate-source voltage; typical values

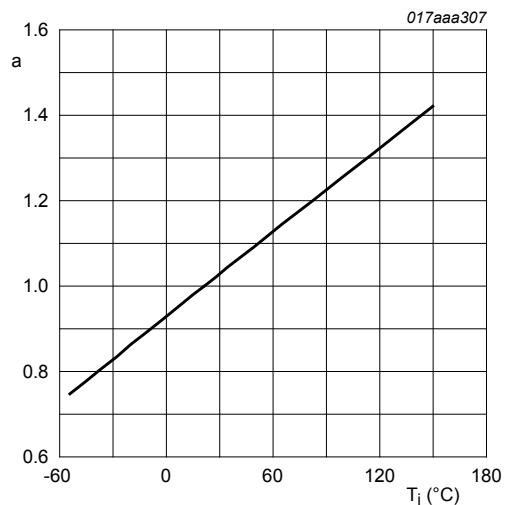
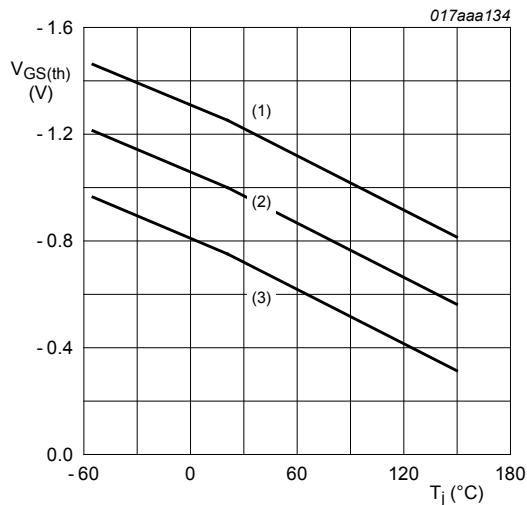


Fig. 11. Normalized drain-source on-state resistance as a function of junction temperature; typical values

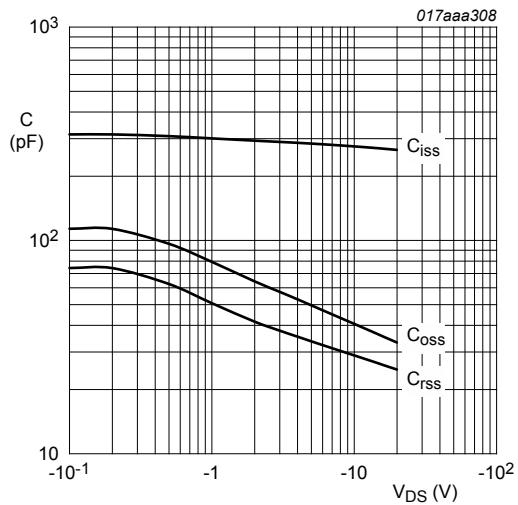
$$a = \frac{R_{DSon}}{R_{DSon}(25^\circ\text{C})}$$



$I_D = -0.25 \text{ mA}; V_{DS} = V_{GS}$

- (1) maximum values
- (2) typical values
- (3) minimum values

Fig. 12. Gate-source threshold voltage as a function of junction temperature



$f = 1 \text{ MHz}; V_{GS} = 0 \text{ V}$

- (1) C_{iss}
- (2) C_{oss}
- (3) C_{rss}

Fig. 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values

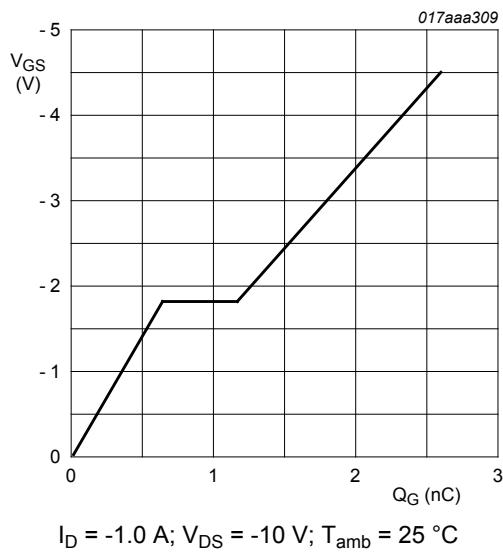


Fig. 14. Gate-source voltage as a function of gate charge; typical values

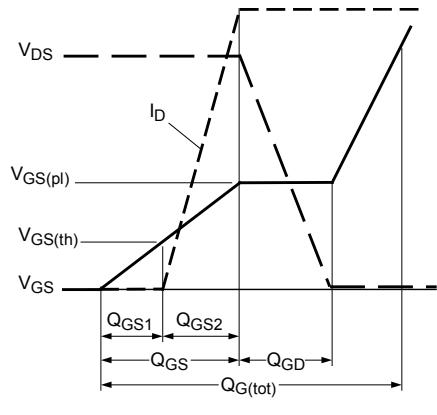
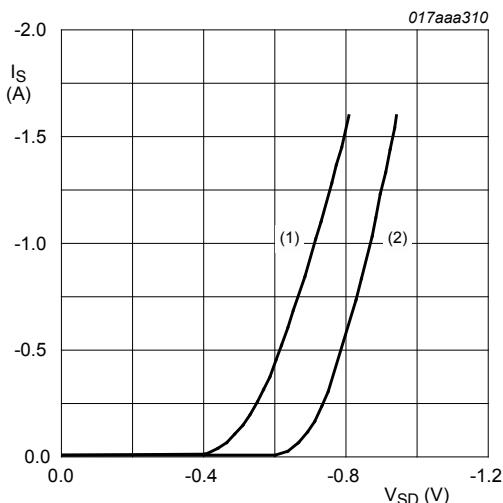


Fig. 15. Gate charge waveform definitions



$V_{GS} = 0$ V
(1) $T_j = 150$ °C
(2) $T_j = 25$ °C

Fig. 16. Source current as a function of source-drain voltage; typical values

11. Test information

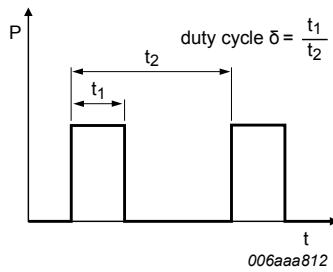


Fig. 17. Duty cycle definition

12. Package outline

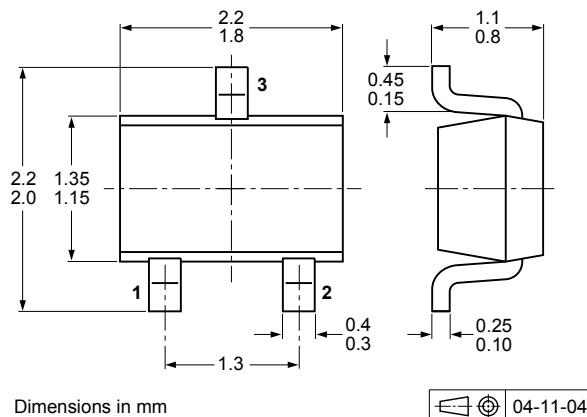
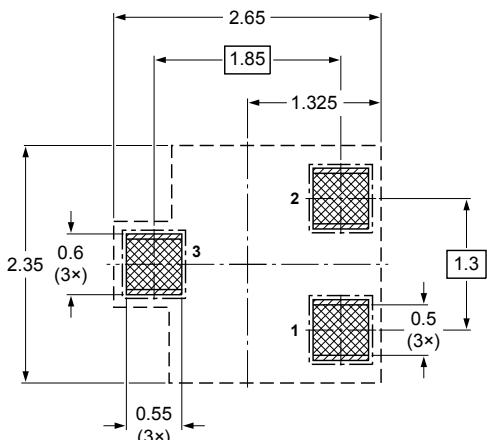


Fig. 18. Package outline SC-70 (SOT323)

13. Soldering



solder lands

solder resist

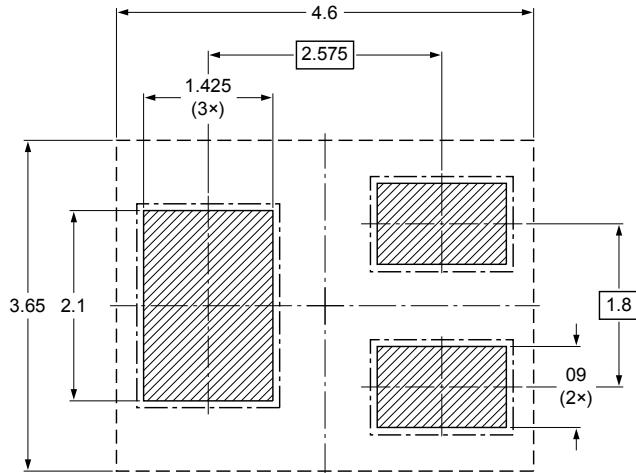
solder paste

occupied area

Dimensions in mm

sot323_fr

Fig. 19. Reflow soldering footprint for SC-70 (SOT323)



solder lands

solder resist

occupied area

Dimensions in mm

preferred transport direction during soldering

sot323_fw

Fig. 20. Wave soldering footprint for SC-70 (SOT323)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMF170XP v.2	20131029	Product data sheet	-	PMF170XP v.1
Modifications:	<ul style="list-style-type: none">Figure 13 corrected			
PMF170XP v.1	20110902	Product data sheet	-	-

15. Legal information

15.1 Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
- [3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nexperia.com>.

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